



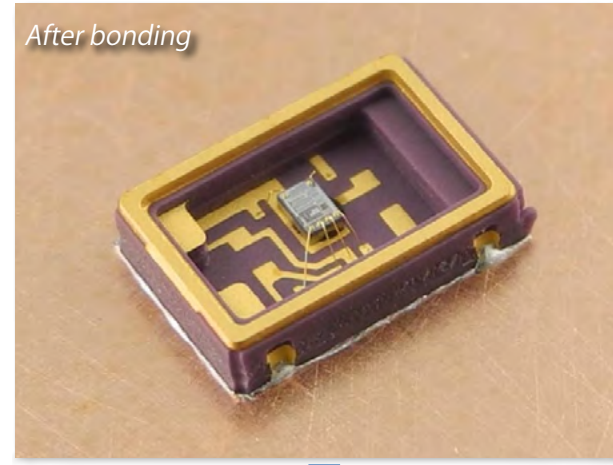
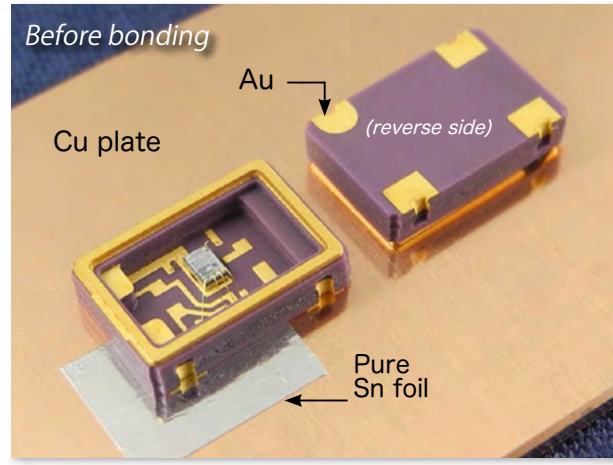
SoundBonding application



<Electronic parts and Copper plate>

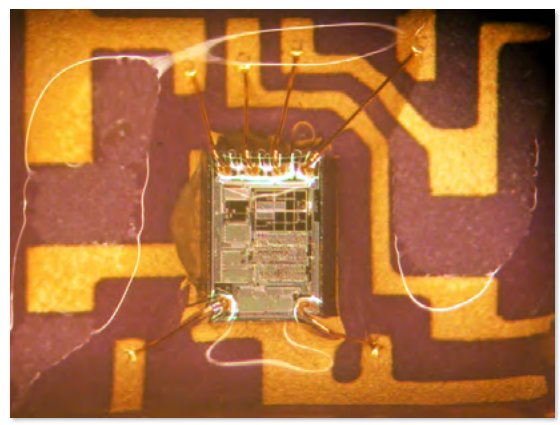
Bonding and Cleaning **without damages to parts**

Bonding of <SAW filter and copper plate> through pure tin foil

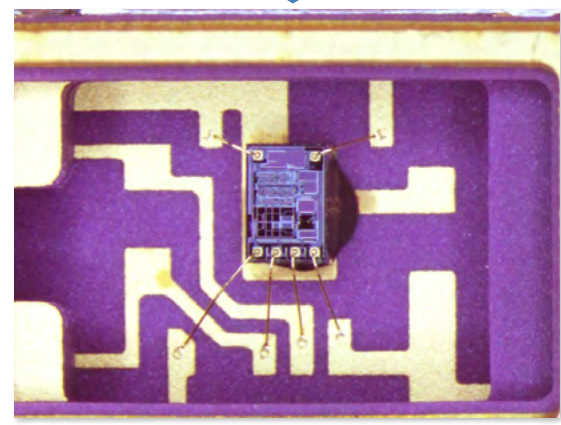


Tin is diffused and <bonded>
Direct bonding is also possible

No damage to the package after cleaning with ULTEX lab system



Gold wires are not disconnected



IC package
Package is not damaged because of no inertia by soundpower

